



Advances in Electrowetting Devices, Volume II

Guest Editor:

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Deadline for manuscript
submissions:

closed (31 January 2024)

Message from the Guest Editor

Dear Colleagues,

Electrowetting has emerged as a new technique with many applications, such as micro-drop generation, manipulation and actuation, sensors, clinical diagnosis, e-paper and electronic display, energy harvesting, beam steering, liquid lenses, and many more. Despite the wide range of application opportunities, the commercialization of electrowetting still faces several challenges, such as charge trapping, oil backflow, contact line instability, dielectric breakdown, reliability in repetitive loading, etc.

This Special Issue aims to inform researchers on the recent advancement of the application of electrowetting techniques, fundamental explanation of related phenomena, development of new material and/or processes, and solution to the challenges of the commercialization of electrowetting devices. This Special Issue is also interested in showcasing a new and novel field of electrowetting applications. The Special Issue will accept diverse forms of contributions, including research papers, communications, methods, and review articles representing the state of the art in electrowetting.





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Message from the Editor-in-Chief

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